



Click [here](#) for the 3D model.

General Information

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|--------------------------|---|
| Series | SMD Indust COG HT200C |
| Style | SMD Chip |
| Description | SMD, MLCC, High Temperature, Ultra-Stable, Low Loss |
| Features | High Temp, Ultra-Stable, Low Loss |
| RoHS | Yes |
| Termination | Gold |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 11 mg |
| Miscellaneous | Moisture Sensitive Packaging. Gold (Au) 1.97 - 11.8 micro inches. |
| Shelf Life | 26 Weeks |
| MSL | 1 |

Dimensions

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|-----------|------------------|
| Chip Size | 0805 |
| L | 2mm +/-0.2mm |
| W | 1.25mm +/-0.2mm |
| T | 0.78mm +/-0.10mm |
| S | 0.7mm MIN |
| B | 0.5mm +/-0.25mm |

Packaging Specifications

| | |
|--------------------|--------------|
| Packaging | Waffle, Tray |
| Packaging Quantity | 100 |

Specifications

| | |
|--|------------------------|
| Capacitance | 0.01 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Tolerance | 5% |
| Voltage DC | 25 VDC |
| Dielectric Withstanding Voltage | 62.5 VDC |
| Temperature Range | -55/+200°C |
| Temp. Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1kHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 kHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 100 GOhms |

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